



### 600V P-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

| BV <sub>DSS</sub> | RDS(ON) Max                  | I <sub>D</sub><br>T <sub>A</sub> = +25°C |
|-------------------|------------------------------|--|
| -600V             | 11Ω @ V <sub>GS</sub> = -10V | -0.27A                                   |

# **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Motor Control
- Backlighting
- AC-DC Converters

## **Features and Benefits**

- Low On-Resistance
- High BV<sub>DSS</sub> Rating for Power Application
- Low Input Capacitance
- Fast Switching
- High Efficiency
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/guality/product-definitions/

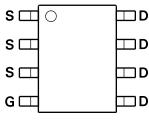
### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 63
- Weight: 0.076 grams (Approximate)

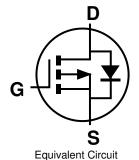
### SO-8 (Standard B)



Top View



Pin-Out Top View



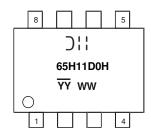
### **Ordering Information** (Note 4)

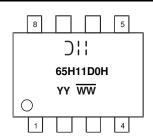
| Part Number      | Case              | Packaging           |
|------------------|-------------------|---------------------|
| DMP65H11D0HSS-13 | SO-8 (Standard B) | 4,000 / Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## **Marking Information**





Oll = Manufacturer's Marking
65H11D0H = Product Type Marking Code
YYWW or YYWW = Date Code Marking
YY or YY = Year (ex: 21 = 2021)
WW or WW = Week (01 to 53)



# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

| Characteristic  | Symbol                                    | Value          | Unit           |      |
|---|---|----------------|----------------|------|
| Drain-Source Voltage (Note 5)   | V <sub>DSS</sub>                          | -600           | V              |      |
| Gate-Source Voltage   | Vgss                                      | ±30            | V              |      |
| Continuous Drain Current (Note 6) V <sub>GS</sub> = -10V                            | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | Ι <sub>D</sub> | -0.27<br>-0.22 | А    |
| Maximum Body Diode Forward Current (Note 6) $TA = +25^{\circ}C$ $TA = +70^{\circ}C$ |   | Is             | -0.27<br>-0.22 | Α    |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)                                  | I <sub>DM</sub>                           | -2.3           | Α              |      |
| Pulsed Source Current (10μs Pulse, Duty Cycle = 1%)                                 | I <sub>SM</sub>                           | -2.3           | Α              |      |
| Peak Diode Recovery dv/dt (Note 8)  |   | dv/dt          | 5              | V/ns |

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic   | Symbol         | Value       | Unit |
|--|----------------|-------------|------|
| Power Dissipation, @T <sub>A</sub> = +25°C (Note 6)                      | PD             | 1.9         | W    |
| Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C (Note 6) | Reja           | 65          | °C/W |
| Power Dissipation, @T <sub>A</sub> = +25°C (Note 7)                      | P <sub>D</sub> | 1.25        | W    |
| Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C (Note 7) | Reja           | 100         | °C/W |
| Operating and Storage Temperature Range                                  | TJ, TSTG       | -55 to +150 | °C   |

# Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic                     | Symbol              | Min  | Тур  | Max  | Unit                                    | Test Condition  |  |
|------------------------------------|---------------------|------|------|------|---|---|--|
| OFF CHARACTERISTICS (Note 9)       | -                   | I.   |      |      | 1                                       | ,   |  |
| Drain-Source Breakdown Voltage     | BV <sub>DSS</sub>   | -650 | _    | _    | V                                       | $V_{GS} = 0V, I_D = -250\mu A$  |  |
| Zero Gate Voltage Drain Current    | IDSS                | _    | _    | -1   | μΑ                                      | V <sub>DS</sub> = -650V, V <sub>GS</sub> = 0V                               |  |
| Gate-Source Leakage                | Igss                | _    | _    | 100  | nA                                      | $V_{GS} = \pm 30V$ , $V_{DS} = 0V$  |  |
| ON CHARACTERISTICS (Note 9)        |                     |      |      |      |   |   |  |
| Gate Threshold Voltage             | V <sub>GS(TH)</sub> | -2   | -3   | -4   | V                                       | $V_{DS} = V_{GS}$ , $I_D = -250\mu A$                                       |  |
| Static Drain-Source On-Resistance  | RDS(ON)             | _    | 8.9  | 11   | Ω                                       | V <sub>GS</sub> = -10V, I <sub>D</sub> = -0.27A                             |  |
| Diode Forward Voltage              | V <sub>SD</sub>     | _    | -0.7 | -1.3 | V                                       | V <sub>GS</sub> = 0V, I <sub>S</sub> = -0.27A                               |  |
| DYNAMIC CHARACTERISTICS (Note 8)   |                     |      | •    | •    |   |   |  |
| Input Capacitance                  | Ciss                | _    | 670  | -    |   | V <sub>DS</sub> = -25V, f = 1MHz,<br>V <sub>GS</sub> = 0V                   |  |
| Output Capacitance                 | Coss                |      | 50   | _    | pF                                      |   |  |
| Reverse Transfer Capacitance       | Crss                | _    | 3.5  | _    |   |   |  |
| Gate Resistance                    | $R_g$               |      | 12   | _    | Ω                                       | $V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$                                  |  |
| Total Gate Charge                  | Qg                  |      | 13   |      |   | V <sub>DD</sub> = -520V, I <sub>D</sub> = -0.27A,<br>V <sub>GS</sub> = -10V |  |
| Gate-Source Charge                 | Qgs                 | _    | 2.6  | _    | nC                                      |   |  |
| Gate-Drain Charge                  | $Q_{gd}$            | _    | 5    | _    |   |   |  |
| Turn-On Delay Time                 | tD(ON)              | _    | 16   | _    |   | $V_{DD} = -325V$ , $V_{GS} = -10V$ , $R_G = 3\Omega$ , $I_D = -0.27A$       |  |
| Turn-On Rise Time                  | tr                  | _    | 10   | _    | 1                                       |   |  |
| Turn-Off Delay Time                | t <sub>D(OFF)</sub> | _    | 46   | _    | ns                                      |   |  |
| Turn-Off Fall Time                 | tF                  | _    | 90   | _    | 1                                       |   |  |
| Body Diode Reverse Recovery Time   | trr                 | _    | 165  | _    | ns                                      | 1 1 11/14 1000/   |  |
| Body Diode Reverse Recovery Charge | Qrr                 | _    | 1.1  | _    | $\mu C$ Is = -1A, dI/dt = 100A/ $\mu$ s |   |  |

Notes: 5. HTRB  $V_{\text{DS}}$  maximum is -480V.

- The Vos infamilian is 400V.
   Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square pad layout.
   Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
   Guaranteed by design. Not subject to production testing.
   Short duration pulse test used to minimize self-heating effect.



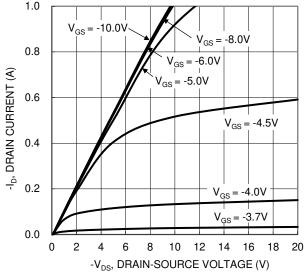


Figure 1. Typical Output Characteristic

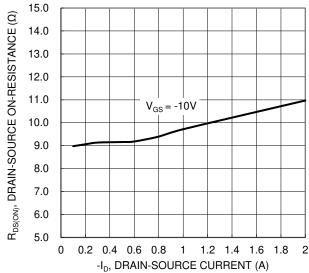


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

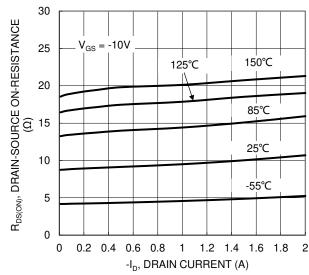


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

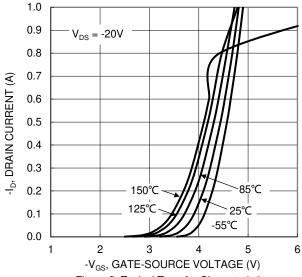


Figure 2. Typical Transfer Characteristic

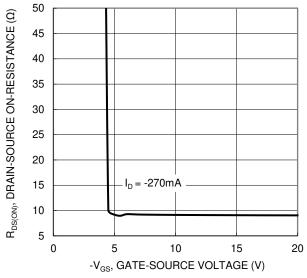


Figure 4. Typical Transfer Characteristic

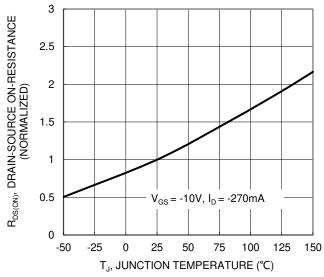


Figure 6. On-Resistance Variation with Temperature



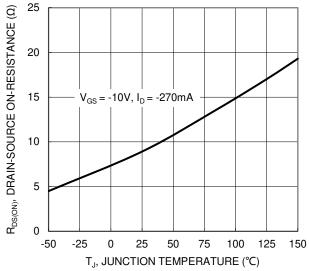


Figure 7. On-Resistance Variation with Temperature

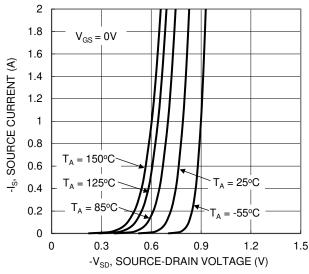
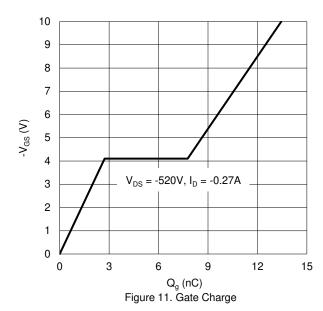


Figure 9. Diode Forward Voltage vs. Current



5 -V $_{GS(TH)}$ , GATE THRESHOLD VOLTAGE (V) 4.5 4 3.5  $I_D = -1mA$ 3 2.5  $I_D = -250 \mu A$ 2 1.5 0.5 -25 -50 0 25 50 75 100 125 150 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 8. Gate Threshold Variation vs. Temperature

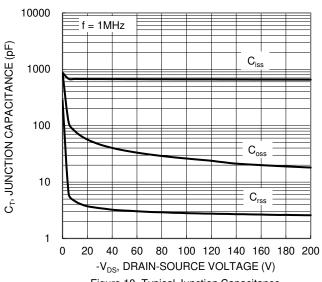


Figure 10. Typical Junction Capacitance

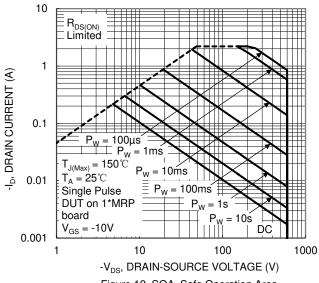


Figure 12. SOA, Safe Operation Area



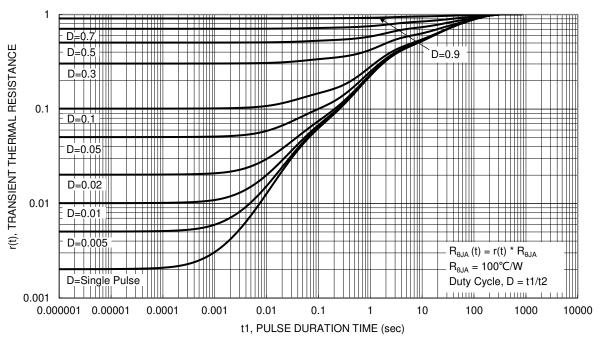


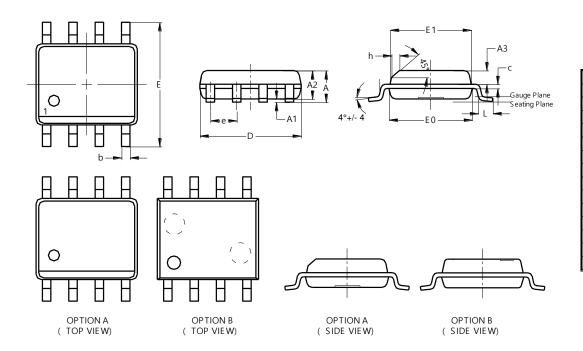
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SO-8 (Standard B)

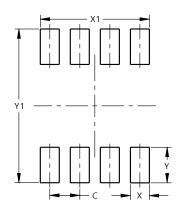


| SO-8 (Standard B)    |      |      |      |  |
|----------------------|------|------|------|--|
| Dim                  | Min  | Max  | Тур  |  |
| Α                    | 1.35 | 1.75 | 1.45 |  |
| <b>A</b> 1           | 0.10 | 0.25 | 0.15 |  |
| A3                   | 0.60 | 0.70 | 0.65 |  |
| b                    | 0.30 | 0.51 | 0.40 |  |
| С                    | 0.15 | 0.25 | 0.20 |  |
| D                    | 4.70 | 5.10 | 4.90 |  |
| Е                    | 5.80 | 6.20 | 6.00 |  |
| E1                   | 3.80 | 3.90 | 3.85 |  |
| E0                   | 3.80 | 4.00 | 3.90 |  |
| е                    |      |      | 1.27 |  |
| h                    |      |      | 0.35 |  |
| L                    | 0.40 | 1.27 |      |  |
| All Dimensions in mm |      |      |      |  |

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SO-8 (Standard B)



| Dimensions | Value (in mm) |  |  |
|------------|---------------|--|--|
| С          | 1.27          |  |  |
| Х          | 0.802         |  |  |
| X1         | 4.612         |  |  |
| Υ          | 1.505         |  |  |
| Y1         | 6.50          |  |  |



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